Si5351A/B/C-B

I²C-PROGRAMMABLE ANY-FREQUENCY CMOS CLOCK GENERATOR + VCXO

Features

- www.silabs.com/custom-timing
- Generates up to 8 non-integer-related frequencies from 8 kHz to 160 MHz
- I²C user definable configuration
- Exact frequency synthesis at each output (0 ppm error)
- Highly linear VCXO
- Optional clock input (CLKIN)
- Low output period jitter: < 70 ps pp, typ
- Configurable spread spectrum selectable at each output
- Operates from a low-cost, fixed frequency crystal: 25 or 27 MHz
- Supports static phase offset
- Programmable rise/fall time control
- Glitchless frequency changes
- Separate voltage supply pins:
  - Core VDD: 2.5 or 3.3 V
  - Output VDDO: 1.8, 2.5, or 3.3 V
- Excellent PSRR eliminates external power supply filtering
- Very low power consumption
- Adjustable output delay
- Available in 2 packages types:
  - 10-MSOP: 3 outputs
  - 20-QFN (4x4 mm): 8 outputs
- PCIE Gen 1 compatible
- Supports HCML compatible swing

Applications

- HDTV, DVD/Blu-ray, set-top box
- Audio/video equipment, gaming
- Printers, scanners, projectors
- Residential gateways
- Networking/communication
- Servers, storage
- XO replacement

Description

The Si5351 is an I²C configurable clock generator that is ideally suited for replacing crystals, crystal oscillators, VCXOs, phase-locked loops (PLLs), and fanout buffers in cost-sensitive applications. Based on a PLL/VCXO + high resolution MultiSynth fractional divider architecture, the Si5351 can generate any frequency up to 160 MHz on each of its outputs with 0 ppm error. Three versions of the Si5351 are available to meet a wide variety of applications. The Si5351A generates up to 8 free-running clocks using an internal oscillator for replacing crystals and crystal oscillators. The Si5351B adds an internal VCXO and provides the flexibility to replace both free-running clocks and synchronous clocks. It eliminates the need for higher cost, custom pullable crystals while providing reliable operation over a wide tuning range. The Si5351C offers the same flexibility but synchronizes to an external reference clock (CLKIN).

Functional Block Diagram

Ordering Information:
See page 28
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## 1. Electrical Specifications

### Table 1. Recommended Operating Conditions

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Test Condition</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Ambient Temperature</td>
<td>$T_A$</td>
<td></td>
<td>−40</td>
<td>25</td>
<td>85</td>
<td>°C</td>
</tr>
<tr>
<td>Core Supply Voltage</td>
<td>$V_{DD}$</td>
<td></td>
<td>3.0</td>
<td>3.3</td>
<td>3.60</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>2.25</td>
<td>2.5</td>
<td>2.75</td>
<td>V</td>
</tr>
<tr>
<td>Output Buffer Voltage</td>
<td>$V_{DDOx}$</td>
<td></td>
<td>1.71</td>
<td>1.8</td>
<td>1.89</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>2.25</td>
<td>2.5</td>
<td>2.75</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>3.0</td>
<td>3.3</td>
<td>3.60</td>
<td>V</td>
</tr>
</tbody>
</table>

**Notes:**
- All minimum and maximum specifications are guaranteed and apply across the recommended operating conditions.
- Typical values apply at nominal supply voltages and an operating temperature of 25 °C unless otherwise noted.
- $VDD$ and $VDDOx$ can be operated at independent voltages.
- Power supply sequencing for $VDD$ and $VDDOx$ requires that all $VDDOx$ be powered up either before or at the same time as $VDD$.

### Table 2. DC Characteristics

($V_{DD} = 2.5 V \pm 10\%$, or $3.3 V \pm 10\%$, $T_A = −40$ to 85 °C)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Test Condition</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Core Supply Current</td>
<td>$I_{DD}$</td>
<td>Enabled 3 outputs</td>
<td>—</td>
<td>22</td>
<td>35</td>
<td>mA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Enabled 8 outputs</td>
<td>—</td>
<td>27</td>
<td>45</td>
<td>mA</td>
</tr>
<tr>
<td>Output Buffer Supply Current</td>
<td>$I_{DDOx}$</td>
<td>$C_L = 5 \text{ pF}$</td>
<td>—</td>
<td>2.2</td>
<td>5</td>
<td>mA</td>
</tr>
<tr>
<td>(Per Output)*</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Input Current</td>
<td>$I_{CLKIN}$</td>
<td>CLkin, SDA, SCL</td>
<td>—</td>
<td>—</td>
<td>10</td>
<td>μA</td>
</tr>
<tr>
<td></td>
<td>$I_{VC}$</td>
<td>$V Cin &lt; 3.6 \text{ V}$</td>
<td>—</td>
<td>—</td>
<td>30</td>
<td>μA</td>
</tr>
<tr>
<td>Output Impedance</td>
<td>$Z_O$</td>
<td>$3.3 \text{ V VDDO}$, default high drive</td>
<td>—</td>
<td>50</td>
<td>—</td>
<td>Ω</td>
</tr>
</tbody>
</table>

**Note:** Output clocks less than or equal to 100 MHz.
### Table 3. AC Characteristics

(V<sub>DD</sub> = 2.5 V ±10%, or 3.3 V ±10%, T<sub>A</sub> = –40 to 85 °C)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Test Condition</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power-up Time</td>
<td>T&lt;sub&gt;RDY&lt;/sub&gt;</td>
<td>From V&lt;sub&gt;DD&lt;/sub&gt; = V&lt;sub&gt;DDmin&lt;/sub&gt; to valid output clock, C&lt;sub&gt;L&lt;/sub&gt; = 5 pF, f&lt;sub&gt;CLKn&lt;/sub&gt; &gt; 1 MHz</td>
<td>—</td>
<td>1</td>
<td>10</td>
<td>ms</td>
</tr>
<tr>
<td>Output Enable Time</td>
<td>T&lt;sub&gt;OE&lt;/sub&gt;</td>
<td>From OEB pulled low to valid clock output, C&lt;sub&gt;L&lt;/sub&gt; = 5 pF, f&lt;sub&gt;CLKn&lt;/sub&gt; &gt; 1 MHz</td>
<td>—</td>
<td>—</td>
<td>10</td>
<td>µs</td>
</tr>
<tr>
<td>Output Phase Offset</td>
<td>P&lt;sub&gt;STEP&lt;/sub&gt;</td>
<td>——</td>
<td>—</td>
<td>333</td>
<td>—</td>
<td>ps/step</td>
</tr>
<tr>
<td>Spread Spectrum Frequency Deviation</td>
<td>SS&lt;sub&gt;DEV&lt;/sub&gt;</td>
<td>Down spread</td>
<td>—0.1</td>
<td>—</td>
<td>—2.5</td>
<td>%</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Center spread</td>
<td>±0.1</td>
<td>—</td>
<td>±1.5</td>
<td>%</td>
</tr>
<tr>
<td>Spread Spectrum Modulation Rate</td>
<td>SS&lt;sub&gt;MOD&lt;/sub&gt;</td>
<td>——</td>
<td>30</td>
<td>31.5</td>
<td>33</td>
<td>kHz</td>
</tr>
</tbody>
</table>

#### VCXO Specifications (Si5351B only)

<table>
<thead>
<tr>
<th>VCXO Control Voltage Range</th>
<th>V&lt;sub&gt;c&lt;/sub&gt;</th>
<th>0</th>
<th>V&lt;sub&gt;DD&lt;/sub&gt;/2</th>
<th>V&lt;sub&gt;DD&lt;/sub&gt;</th>
<th>V</th>
<th>ppm/V</th>
</tr>
</thead>
<tbody>
<tr>
<td>VCXO Gain (configurable)</td>
<td>K&lt;sub&gt;v&lt;/sub&gt;</td>
<td>V&lt;sub&gt;c&lt;/sub&gt; = 10–90% of V&lt;sub&gt;DD&lt;/sub&gt;, V&lt;sub&gt;DD&lt;/sub&gt; = 3.3 V</td>
<td>18</td>
<td>—</td>
<td>150</td>
<td></td>
</tr>
<tr>
<td>VCXO Control Voltage Linearity</td>
<td>K&lt;sub&gt;VL&lt;/sub&gt;</td>
<td>V&lt;sub&gt;c&lt;/sub&gt; = 10–90% of V&lt;sub&gt;DD&lt;/sub&gt;</td>
<td>—5</td>
<td>—</td>
<td>+5</td>
<td>%</td>
</tr>
<tr>
<td>VCXO Pull Range (configurable)</td>
<td>PR</td>
<td>V&lt;sub&gt;DD&lt;/sub&gt; = 3.3 V*</td>
<td>±30</td>
<td>0</td>
<td>±240</td>
<td>ppm</td>
</tr>
<tr>
<td>VCXO Modulation Bandwidth</td>
<td>——</td>
<td>—</td>
<td>10</td>
<td>—</td>
<td>kHz</td>
<td></td>
</tr>
</tbody>
</table>

*Note: Contact Silicon Labs for 2.5 V VCXO operation.*

### Table 4. Input Clock Characteristics

(V<sub>DD</sub> = 2.5 V ±10%, or 3.3 V ±10%, T<sub>A</sub> = –40 to 85 °C)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Test Condition</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>CLKIN Input Low Voltage</td>
<td>V&lt;sub&gt;IL&lt;/sub&gt;</td>
<td>—0.1</td>
<td>—</td>
<td>0.3 x V&lt;sub&gt;DD&lt;/sub&gt;</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>CLKIN Input High Voltage</td>
<td>V&lt;sub&gt;IH&lt;/sub&gt;</td>
<td>0.7 x V&lt;sub&gt;DD&lt;/sub&gt;</td>
<td>—</td>
<td>3.60</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>CLKIN Frequency Range</td>
<td>f&lt;sub&gt;CLKIN&lt;/sub&gt;</td>
<td>10</td>
<td>—</td>
<td>100</td>
<td>MHz</td>
<td></td>
</tr>
</tbody>
</table>
### Table 5. Output Clock Characteristics

(VDD = 2.5 V ±10%, or 3.3 V ±10%, TA = –40 to 85 °C)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Test Condition</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Frequency Range</td>
<td>F_CLK</td>
<td></td>
<td>0.008</td>
<td>—</td>
<td>160</td>
<td>MHz</td>
</tr>
<tr>
<td>Load Capacitance</td>
<td>C_L</td>
<td>Measured at VDD/2, f_CLK = 50 MHz</td>
<td>—</td>
<td>—</td>
<td>15</td>
<td>pF</td>
</tr>
<tr>
<td>Duty Cycle</td>
<td>DC</td>
<td>Measured at VDD/2, f_CLK = 50 MHz</td>
<td>45</td>
<td>50</td>
<td>55</td>
<td>%</td>
</tr>
<tr>
<td>Rise/Fall Time</td>
<td>t_r</td>
<td>20%–80%, C_L = 5 pF, Default high drive strength</td>
<td>—</td>
<td>1</td>
<td>1.5</td>
<td>ns</td>
</tr>
<tr>
<td></td>
<td>t_f</td>
<td>20%–80%, C_L = 5 pF, Default high drive strength</td>
<td>—</td>
<td>1</td>
<td>1.5</td>
<td>ns</td>
</tr>
<tr>
<td>Output High Voltage</td>
<td>V_OH</td>
<td>C_L = 5 pF</td>
<td>V_DD –0.6</td>
<td>—</td>
<td>—</td>
<td>V</td>
</tr>
<tr>
<td>Output Low Voltage</td>
<td>V_OL</td>
<td></td>
<td>—</td>
<td>—</td>
<td>0.6</td>
<td>V</td>
</tr>
<tr>
<td>Period Jitter*</td>
<td>J_PER</td>
<td>20-QFN, 4 outputs running, 1 per VDDO</td>
<td>—</td>
<td>40</td>
<td>95</td>
<td>ps, pk-pk</td>
</tr>
<tr>
<td></td>
<td></td>
<td>10-MSOP or 20-QFN, all outputs running</td>
<td>—</td>
<td>70</td>
<td>140</td>
<td>ps, pk-pk</td>
</tr>
<tr>
<td>Cycle-to-Cycle Jitter*</td>
<td>J_CC</td>
<td>20-QFN, 4 outputs running, 1 per VDDO</td>
<td>—</td>
<td>50</td>
<td>90</td>
<td>ps, pk</td>
</tr>
<tr>
<td></td>
<td></td>
<td>10-MSOP or 20-QFN, all outputs running</td>
<td>—</td>
<td>70</td>
<td>130</td>
<td>ps, pk</td>
</tr>
<tr>
<td>Period Jitter VCXO*</td>
<td>J_PER VCXO</td>
<td>20-QFN, 4 outputs running, 1 per VDDO</td>
<td>—</td>
<td>50</td>
<td>95</td>
<td>ps, pk-pk</td>
</tr>
<tr>
<td></td>
<td></td>
<td>10-MSOP or 20-QFN, all outputs running</td>
<td>—</td>
<td>70</td>
<td>150</td>
<td>ps, pk-pk</td>
</tr>
<tr>
<td>Cycle-to-Cycle Jitter VCXO*</td>
<td>J_CC VCXO</td>
<td>20-QFN, 4 outputs running, 1 per VDDO</td>
<td>—</td>
<td>50</td>
<td>90</td>
<td>ps, pk</td>
</tr>
<tr>
<td></td>
<td></td>
<td>10-MSOP or 20-QFN, all outputs running</td>
<td>—</td>
<td>70</td>
<td>140</td>
<td>ps, pk</td>
</tr>
</tbody>
</table>

*Note: Measured over 10k cycles. Jitter is highly dependent on device frequency configuration. Specifications represent a "worst case, real world" frequency plan; actual performance may be substantially better. For 3 output 10-MSOP package, measured with clock outputs of 74.25, 24.576, 48 MHz. For 8 output 20-QFN package, measured with clock outputs of 33.33, 74.25, 27, 24.576, 22.5792, 28.322, 125, 48 MHz.
### Table 6. Crystal Requirements\(^1,2\)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Crystal Frequency</td>
<td>(f_{XTAL})</td>
<td>25</td>
<td>—</td>
<td>27</td>
<td>MHz</td>
</tr>
<tr>
<td>Load Capacitance</td>
<td>(C_L)</td>
<td>6</td>
<td>—</td>
<td>12</td>
<td>(\mu F)</td>
</tr>
<tr>
<td>Equivalent Series Resistance</td>
<td>(r_{ESR})</td>
<td>—</td>
<td>—</td>
<td>150</td>
<td>(\Omega)</td>
</tr>
<tr>
<td>Crystal Max Drive Level</td>
<td>(d_L)</td>
<td>—</td>
<td>—</td>
<td>100</td>
<td>(\mu W)</td>
</tr>
</tbody>
</table>

**Notes:**
1. Crystals which require load capacitances of 6, 8, or 10 \(\mu F\) should use the device’s internal load capacitance for optimum performance. See register 183 bits 7:6. A crystal with a 12 \(\mu F\) load capacitance requirement should use a combination of the internal 10 \(\mu F\) load capacitors in addition to external 2 \(\mu F\) load capacitors.
2. Refer to “AN551: Crystal Selection Guide” for more details.

### Table 7. \(^2\)C Specifications (SCL,SDA)\(^1\)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Test Condition</th>
<th>Standard Mode 100 kbps</th>
<th>Fast Mode 400 kbps</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>LOW Level Input Voltage</td>
<td>(V_{IL2C})</td>
<td></td>
<td>Min</td>
<td>Max</td>
<td>Min</td>
</tr>
<tr>
<td>HIGH Level Input Voltage</td>
<td>(V_{IH2C})</td>
<td></td>
<td>0.7 (V_{DDI2C})</td>
<td>3.6</td>
<td>0.7 (V_{DDI2C})</td>
</tr>
<tr>
<td>Hysteresis of Schmitt Trigger Inputs</td>
<td>(V_{HYS})</td>
<td></td>
<td>—</td>
<td>—</td>
<td>0.1</td>
</tr>
<tr>
<td>LOW Level Output Voltage (open drain or open collector) at 3 mA Sink Current</td>
<td>(V_{OL2C})</td>
<td>(V_{DDI2C} = 2.5/3.3 V)</td>
<td>0</td>
<td>0.4</td>
<td>0</td>
</tr>
<tr>
<td>Input Current</td>
<td>(I_{II2C})</td>
<td></td>
<td>—10</td>
<td>10</td>
<td>—10</td>
</tr>
<tr>
<td>Capacitance for Each I/O Pin</td>
<td>(C_{II2C})</td>
<td>(V_{IN} = –0.1 \text{ to } V_{DDI2C})</td>
<td>—</td>
<td>4</td>
<td>—</td>
</tr>
<tr>
<td>(^2)C Bus Timeout</td>
<td>(T_{TO})</td>
<td>Timeout Enabled</td>
<td>25</td>
<td>35</td>
<td>25</td>
</tr>
</tbody>
</table>

**Notes:**
2. Only \(^2\)C pullup voltages (VDDI2C) of 2.25 to 3.63 \(V\) are supported.
### Table 8. Thermal Characteristics

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Test Condition</th>
<th>Package</th>
<th>Value</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Thermal Resistance</td>
<td>( \theta_{JA} )</td>
<td>Still Air</td>
<td>10-MSOP</td>
<td>131</td>
<td>°C/W</td>
</tr>
<tr>
<td>Junction to Ambient</td>
<td></td>
<td></td>
<td>20-QFN</td>
<td>51</td>
<td>°C/W</td>
</tr>
<tr>
<td>Thermal Resistance</td>
<td>( \theta_{JC} )</td>
<td>Still Air</td>
<td>10-MSOP</td>
<td>43</td>
<td>°C/W</td>
</tr>
<tr>
<td>Junction to Case</td>
<td></td>
<td></td>
<td>20-QFN</td>
<td>16</td>
<td>°C/W</td>
</tr>
</tbody>
</table>

### Table 9. Absolute Maximum Ratings

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Test Condition</th>
<th>Value</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>DC Supply Voltage</td>
<td>( V_{DD_max} )</td>
<td>CLKN, SCL, SDA</td>
<td>–0.5 to 3.8 V</td>
<td>V</td>
</tr>
<tr>
<td>Input Voltage</td>
<td>( V_{IN_CLKIN} )</td>
<td>CLKN, SCL, SDA</td>
<td>–0.5 to 3.8 V</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td>( V_{IN_VC} )</td>
<td>VC</td>
<td>–0.5 to (VDD+0.3) V</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td>( V_{IN_XA/B} )</td>
<td>Pins XA, XB</td>
<td>–0.5 to 1.3 V</td>
<td>V</td>
</tr>
<tr>
<td>Junction Temperature</td>
<td>( T_J )</td>
<td></td>
<td>–55 to 150 °C</td>
<td></td>
</tr>
<tr>
<td>Soldering Temperature (Pb-free profile)</td>
<td>( T_{PEAK} )</td>
<td></td>
<td>260 °C</td>
<td></td>
</tr>
<tr>
<td>Soldering Temperature Time at TPEAK (Pb-free profile)</td>
<td>( T_P )</td>
<td></td>
<td>20–40 Sec</td>
<td></td>
</tr>
</tbody>
</table>

**Notes:**

1. Permanent device damage may occur if the absolute maximum ratings are exceeded. Functional operation should be restricted to the conditions as specified in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

2. The device is compliant with JEDEC J-STD-020.
2. Detailed Block Diagrams

Figure 1. Block Diagrams of 3-Output and 8-Output Si5351A Devices
Figure 2. Block Diagrams of Si5351B and Si5351C 8-Output Devices
3. Functional Description

The Si5351 is a versatile I^2C programmable clock generator that is ideally suited for replacing crystals, crystal oscillators, VCXOs, PLLs, and buffers. A block diagram showing the general architecture of the Si5351 is shown in Figure 3. The device consists of an input stage, two synthesis stages, and an output stage.

The input stage accepts an external crystal (XTAL), a control voltage input (VC), or a clock input (CLKin) depending on the version of the device (A/B/C). The first stage of synthesis multiplies the input frequencies to an high-frequency intermediate clock, while the second stage of synthesis uses high resolution MultiSynth fractional dividers to generate the desired output frequencies. Additional integer division is provided at the output stage for generating output frequencies as low as 8 kHz. Crosspoint switches at each of the synthesis stages allows total flexibility in routing any of the inputs to any of the outputs.

Because of this high resolution and flexible synthesis architecture, the Si5351 is capable of generating synchronous or free-running non-integer related clock frequencies at each of its outputs, enabling one device to synthesize clocks for multiple clock domains in a design.

![Figure 3. Si5351 Block Diagram](image-url)
3.1. Input Stage

3.1.1. Crystal Inputs (XA, XB)

The Si5351 uses a fixed-frequency standard AT-cut crystal as a reference to the internal oscillator. The output of the oscillator can be used to provide a free-running reference to one or both of the PLLs for generating asynchronous clocks. The output frequency of the oscillator will operate at the crystal frequency, either 25 MHz or 27 MHz. The crystal is also used as a reference to the VCXO to help maintain its frequency accuracy.

Internal load capacitors ($C_L$) are provided to eliminate the need for external components when connecting a crystal to the Si5351. Options for internal load capacitors are 6, 8, or 10 pF. Crystals with alternate load capacitance requirements are supported using additional external load capacitors as shown in Figure 4. Refer to application note AN551 for crystal recommendations.

![Figure 4. External XTAL with Optional Load Capacitors](image)

3.1.2. External Clock Input (CLKIN)

The external clock input is used as a clock reference for the PLLs when generating synchronous clock outputs. CLKIN can accept any frequency from 10 to 100 MHz. A divider at the input stage limits the PLL input frequency to 30 MHz.

3.1.3. Voltage Control Input (VC)

The VCXO architecture of the Si5350B eliminates the need for an external pullable crystal. Only a standard, low-cost, fixed-frequency (25 or 27 MHz) AT-cut crystal is required.

The tuning range of the VCXO is configurable allowing for a wide variety of applications. Key advantages of the VCXO design in the Si5351 include high linearity, a wide operating range (linear from 10 to 90% of VDD), and reliable startup and operation. Refer to Table 3 on page 5 for VCXO specification details.

A unique feature of the Si5351B is its ability to generate multiple output frequencies controlled by the same control voltage applied to the VC pin. This replaces multiple PLLs or VCXOs that would normally be locked to the same reference. An example is illustrated in Figure 5 on page 13.
3.2. Synthesis Stages

The Si5351 uses two stages of synthesis to generate its final output clocks. The first stage uses PLLs to multiply the lower frequency input references to a high-frequency intermediate clock. The second stage uses high-resolution MultiSynth fractional dividers to generate frequencies in the range of 1 MHz to 112.5 MHz. It is also possible to generate two unique frequencies up to 160 MHz on two or more of the outputs.

A crosspoint switch at the input of the first stage allows each of the PLLs to lock to the CLKin or the XTAL input. This allows each of the PLLs to lock to a different source for generating independent free-running and synchronous clocks. Alternatively, both PLLs could lock to the same source. The crosspoint switch at the input of the second stage allows any of the MultiSynth dividers to connect to PLLA or PLLB. This flexible synthesis architecture allows any of the outputs to generate synchronous or non-synchronous clocks, with spread spectrum or without spread spectrum, and with the flexibility of generating non-integer related clock frequencies at each output.

All VCXO outputs are generated by PLLB only. The Multisynth high-resolution dividers can synthesize VCXO outputs with center frequencies up to 112.5 MHz. The center frequency is then controlled (or pulled) by the VC input. An interesting feature of the Si5351 is that the VCXO output can be routed to more than one MultiSynth divider. This creates a VCXO with multiple output frequencies controlled from one VC input as shown in Figure 5.

Frequencies down to 8 kHz can be generated by applying the R divider at the output of the Multisynth (see Figure 5 below).

![Figure 5. Using the Si5351 as a Multi-Output VCXO](image-url)
3.3. Output Stage
An additional level of division (R) is available at the output stage for generating clocks as low as 8 kHz. All output drivers generate CMOS level outputs with separate output voltage supply pins (VDDOx) allowing a different voltage signal level (1.8, 2.5, or 3.3 V) at each of the four 2-output banks.

3.4. Spread Spectrum
Spread spectrum can be enabled on any of the clock outputs that use PLLA as its reference. Spread spectrum is useful for reducing electromagnetic interference (EMI). Enabling spread spectrum on an output clock modulates its frequency, which effectively reduces the overall amplitude of its radiated energy. Note that spread spectrum is not available on clocks synchronized to PLLB or to the VCXO.

The Si5351 supports several levels of spread spectrum allowing the designer to chose an ideal compromise between system performance and EMI compliance.

3.5. Control Pins (OEB, SSEN)
The Si5351 offers control pins for enabling/disabling clock outputs and spread spectrum.

3.5.1. Output Enable (OEB)
The output enable pin allows enabling or disabling outputs clocks. Output clocks are enabled when the OEB pin is held low, and disabled when pulled high. When disabled, the output state is configurable as output high, output low, or high-impedance.

The output enable control circuitry ensures glitchless operation by starting the output clock cycle on the first leading edge after OEB is pulled low. When OEB is pulled high, the clock is allowed to complete its full clock cycle before going into a disabled state.

3.5.2. Spread Spectrum Enable (SSEN)—Si5351A and Si5351B only
This control pin allows disabling the spread spectrum feature for all outputs that were configured with spread spectrum enabled. Hold SSEN low to disable spread spectrum. The SSEN pin provides a convenient method of evaluating the effect of using spread spectrum clocks during EMI compliance testing.

Figure 6. Available Spread Spectrum Profiles
4. **I²C Interface**

Many of the functions and features of the Si5351 are controlled by reading and writing to the RAM space using the I²C interface. The following is a list of the common features that are controllable through the I²C interface.

**Read Status Indicators**

- Crystal Reference Loss of signal, LOS_XTAL, reg0[3]
- CLKIN Loss of signal, LOS_CLKIN, reg0[4]
- PLLA and/or PLLB Loss of lock, LOL_A or LOL_B, reg0[6:5]
- Configuration of multiplication and divider values for the PLLs, MultiSynth dividers
- Configuration of the Spread Spectrum profile (down or center spread, modulation percentage)
- Control of the cross point switch selection for each of the PLLs and MultiSynth dividers
- Set output clock options
  - Enable/disable for each clock output
  - Invert/non-invert for each clock output
  - Output divider values \(2^n\), \(n=1...7\)
  - Output state when disabled (stop hi, stop low, Hi-Z)
  - Output phase offset

The I²C interface operates in slave mode with 7-bit addressing and can operate in Standard-Mode (100 kbps) or Fast-Mode (400 kbps) and supports burst data transfer with auto address increments.

The I²C bus consists of a bidirectional serial data line (SDA) and a serial clock input (SCL) as shown in Figure 7. Both the SDA and SCL pins must be connected to the VDD supply via an external pull-up as recommended by the I²C specification.

**Figure 7. I²C and Control Signals**

The 7-bit device (slave) address of the Si5351 consist of a 6-bit fixed address plus a user selectable LSB bit as shown in Figure 8. The LSB bit is selectable as 0 or 1 using the optional A0 pin which is useful for applications that require more than one Si5351 on a single I²C bus.

![Si5351 I²C Slave Address](image)

**Figure 8. Si5351 I²C Slave Address**

Data is transferred MSB first in 8-bit words as specified by the I²C specification. A write command consists of a 7-bit device (slave) address + a write bit, an 8-bit register address, and 8 bits of data as shown in Figure 9. A write burst operation is also shown where every additional data word is written using to an auto-incremented address.
Figure 9. I²C Write Operation

A read operation is performed in two stages. A data write is used to set the register address, then a data read is performed to retrieve the data from the set address. A read burst operation is also supported. This is shown in Figure 10.

Figure 10. I²C Read Operation

AC and DC electrical specifications for the SCL and SDA pins are shown in Table 7. The timing specifications and timing diagram for the I²C bus is compatible with the I²C-Bus Standard. SDA timeout is supported for compatibility with SMBus interfaces.
5. Configuring the Si5351

The Si5351 is a highly flexible clock generator which is entirely configurable through its I²C interface. The device’s default configuration is stored in non-volatile memory (NVM) as shown in Figure 11. The NVM is a one time programmable memory (OTP) which can store a custom user configuration at power-up. This is a useful feature for applications that need a clock present at power-up (e.g., for providing a clock to a processor).

![Si5351 Memory Configuration Diagram]

**Figure 11. Si5351 Memory Configuration**

During a power cycle the contents of the NVM are copied into random access memory (RAM), which sets the device configuration that will be used during normal operation. Any changes to the device configuration after power-up are made by reading and writing to registers in the RAM space through the I²C interface.

5.1. Writing a Custom Configuration to RAM

To simplify device configuration, Silicon Labs has released the ClockBuilder Desktop. The software serves two purposes: to configure the Si5351 with optimal configuration based on the desired frequencies and to control the EVB when connected to a host PC.

The optimal configuration can be saved from the software in text files that can be used in any system, which configures the device over I²C. ClockBuilder Desktop can be downloaded from www.silabs.com/ClockBuilder and runs on Windows XP, Windows Vista, and Windows 7.

Once the configuration file has been saved, the device can be programmed via I²C by following the steps shown in Figure 12.
Figure 12. I\textsuperscript{2}C Programming Procedure

1. Disable Outputs
   Set CLKx_DIS high; Reg. 3 = 0xFF

2. Powerdown all output drivers
   Reg. 16, 17, 18, 19, 20, 21, 22, 23 = 0x80

3. Set interrupt masks
   (see register 2 description)

4. Write new configuration to device using
   the contents of the register map
   generated by ClockBuilder Desktop. This
   step also powers up the output drivers.
   (Registers 15-92, 149-170 and 183)

5. Apply PLLA and PLLB soft reset
   Reg. 177 = 0xAC

6. Enable desired outputs
   (see Register 3)

Use ClockBuilder Desktop v3.1 or later
5.2. Si5351 Application Examples

The Si5351 is a versatile clock generator which serves a wide variety of applications. The following examples show how it can be used to replace crystals, crystal oscillators, VCXOs, and PLLs.

5.3. Replacing Crystals and Crystal Oscillators

Using an inexpensive external crystal, the Si5351A can generate up to 8 different free-running clock frequencies for replacing crystals and crystal oscillators. A 3-output version packaged in a small 10-MSOP is also available for applications that require fewer clocks. An example is shown in Figure 13.

5.4. Replacing Crystals, Crystal Oscillators, and VCXOs

The Si5351B combines free-running clock generation and a VCXO in a single package for cost sensitive video applications. An example is shown in Figure 14.
5.5. Replacing Crystals, Crystal Oscillators, and PLLs
The Si5350C generates synchronous clocks for applications that require a fully integrated PLL instead of a VCXO. Because of its dual PLL architecture, the Si5351C is capable of generating both synchronous and free-running clocks. An example is shown in Figure 15.

![Figure 15. Using the Si5351C to Replace Crystals, Crystal Oscillators, and PLLs](image)

5.6. Applying a Reference Clock at XTAL Input
The Si5351 can be driven with a clock signal through the XA input pin. This is especially useful when in need of generating clock outputs in two synchronization domains. With the Si5351C, one reference clock can be provided at the CLKIN pin and at XA.

![Figure 16. Si5351 Driven by a Clock Signal](image)

Note: Float the XB input while driving the XA input with a clock

\[ V_{in} = 1 \, V_{pp} \]

25/27 MHz

0.1 µF
5.7. HCSL Compatible Outputs

The Si5351 can be configured to support HCSL compatible swing when the VDDO of the output pair of interest is set to 2.5 V (i.e., VDDOA must be 2.5 V when using CLK0/1; VDDOB must be 2.5 V for CLK2/3 and so on).

The circuit in the figure below must be applied to each of the two clocks used, and one of the clocks in the pair must also be inverted to generate a differential pair. See register setting CLKx_INV.

![Figure 17. Si5351 Output is HCSL Compatible](image)
6. Design Considerations

The Si5351 is a self-contained clock generator that requires very few external components. The following general guidelines are recommended to ensure optimum performance. Refer to "AN554: Si5350/51 PCB Layout Guide" for additional layout recommendations.

6.1. Power Supply Decoupling/Filtering

The Si5351 has built-in power supply filtering circuitry and extensive internal Low Drop Out (LDO) voltage regulators to help minimize the number of external bypass components. All that is recommended is one 0.1 to 1.0 µF decoupling capacitor per power supply pin. This capacitor should be mounted as close to the VDD and VDDOx pins as possible without using vias.

6.2. Power Supply Sequencing

The VDD and VDDOx (i.e., VDDO0, VDDO1, VDDO2, VDDO3) power supply pins have been separated to allow flexibility in output signal levels. If a minimum output-to-output skew is important, then all VDDOx must be applied before VDD. Unused VDDOx pins should be tied to VDD.

6.3. External Crystal

The external crystal should be mounted as close to the pins as possible using short PCB traces. The XA and XB traces should be kept away from other high-speed signal traces. See "AN551: Crystal Selection Guide" for more details.

6.4. External Crystal Load Capacitors

The Si5351 provides the option of using internal and external crystal load capacitors. If internal load capacitance is insufficient, capacitors of value ≤ 2 pF may be used to increased equivalent load capacitance. If external load capacitors are used, they should be placed as close to the XA/XB pads as possible. See "AN551: Crystal Selection Guide" for more details.

6.5. Unused Pins

Unused voltage control pin should be tied to GND.
Unused CLKin pin should be tied to GND.
Unused XA/XB pins should be left floating. Refer to "5.6. Applying a Reference Clock at XTAL Input" on page 20 when using XA as a clock input pin.
Unused output pins (CLK0–CLK7) should be left floating.
Unused VDDOx pins should be tied to VDD.

6.6. Trace Characteristics

The Si5351A/B/C features various output current drive strengths. It is recommended to configure the trace characteristics as shown in Figure 18 when the default high drive strength is used.

![Figure 18. Recommended Trace Characteristics with Default Drive Strength Setting](image)

Note: Jitter is only specified at default high drive strength.
7. Register Map Summary

For many applications, the Si5351’s register values are easily configured using ClockBuilder Desktop software. However, for customers interested in using the Si5351 in operating modes beyond the capabilities available with ClockBuilder™, refer to “AN619: Manually Generating an Si5351 Register Map” for a detailed description of the Si5351 registers and their usage.

8. Register Descriptions

Refer to “AN619: Manually Generating an Si5351 Register Map” for a detailed description of Si5351 registers.
Si5351A/B/C-B

9. Si5351 Pin Descriptions

9.1. Si5351A 20-pin QFN

Table 10. Si5351A Pin Descriptions

<table>
<thead>
<tr>
<th>Pin Name</th>
<th>Pin Number</th>
<th>Pin Type</th>
<th>Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>XA</td>
<td>1</td>
<td>I</td>
<td>Input pin for external crystal.</td>
</tr>
<tr>
<td>XB</td>
<td>2</td>
<td>I</td>
<td>Input pin for external crystal.</td>
</tr>
<tr>
<td>CLK0</td>
<td>13</td>
<td>O</td>
<td>Output clock 0.</td>
</tr>
<tr>
<td>CLK1</td>
<td>12</td>
<td>O</td>
<td>Output clock 1.</td>
</tr>
<tr>
<td>CLK2</td>
<td>9</td>
<td>O</td>
<td>Output clock 2.</td>
</tr>
<tr>
<td>CLK3</td>
<td>8</td>
<td>O</td>
<td>Output clock 3.</td>
</tr>
<tr>
<td>CLK4</td>
<td>19</td>
<td>O</td>
<td>Output clock 4.</td>
</tr>
<tr>
<td>CLK5</td>
<td>17</td>
<td>O</td>
<td>Output clock 5.</td>
</tr>
<tr>
<td>CLK6</td>
<td>16</td>
<td>O</td>
<td>Output clock 6.</td>
</tr>
<tr>
<td>CLK7</td>
<td>15</td>
<td>O</td>
<td>Output clock 7.</td>
</tr>
<tr>
<td>A0</td>
<td>3</td>
<td>I</td>
<td>I²C address bit.</td>
</tr>
<tr>
<td>SCL</td>
<td>4</td>
<td>I</td>
<td>I²C bus serial clock input. Pull-up to VDD core with 1 kΩ.</td>
</tr>
<tr>
<td>SDA</td>
<td>5</td>
<td>I/O</td>
<td>I²C bus serial data input. Pull-up to VDD core with 1 kΩ.</td>
</tr>
<tr>
<td>SSEN</td>
<td>6</td>
<td>I</td>
<td>Spread spectrum enable. High = enabled, Low = disabled.</td>
</tr>
<tr>
<td>OEB</td>
<td>7</td>
<td>I</td>
<td>Output driver enable. Low = enabled, High = disabled.</td>
</tr>
<tr>
<td>VDD</td>
<td>20</td>
<td>P</td>
<td>Core voltage supply pin. See 6.2.</td>
</tr>
<tr>
<td>VDDOA</td>
<td>11</td>
<td>P</td>
<td>Output voltage supply pin for CLK0 and CLK1. See 6.2.</td>
</tr>
<tr>
<td>VDDOB</td>
<td>10</td>
<td>P</td>
<td>Output voltage supply pin for CLK2 and CLK3. See 6.2.</td>
</tr>
<tr>
<td>VDDOC</td>
<td>18</td>
<td>P</td>
<td>Output voltage supply pin for CLK4 and CLK5. See 6.2.</td>
</tr>
<tr>
<td>VDDOD</td>
<td>14</td>
<td>P</td>
<td>Output voltage supply pin for CLK6 and CLK7. See 6.2.</td>
</tr>
<tr>
<td>GND</td>
<td>Center Pad</td>
<td>P</td>
<td>Ground. Use multiple vias to ensure a solid path to GND.</td>
</tr>
</tbody>
</table>

1. I = Input, O = Output, P = Power.
2. Input pins are not internally pulled up.
9.2. Si5351B 20-Pin QFN

![Figure 20. Si5351B 20-QFN Top View*](image)

### Table 11. Si5351B Pin Descriptions

<table>
<thead>
<tr>
<th>Pin Name</th>
<th>Pin Number</th>
<th>Pin Type</th>
<th>Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>XA</td>
<td>1</td>
<td>I</td>
<td>Input pin for external crystal</td>
</tr>
<tr>
<td>XB</td>
<td>2</td>
<td>I</td>
<td>Input pin for external crystal</td>
</tr>
<tr>
<td>CLK0</td>
<td>13</td>
<td>O</td>
<td>Output clock 0</td>
</tr>
<tr>
<td>CLK1</td>
<td>12</td>
<td>O</td>
<td>Output clock 1</td>
</tr>
<tr>
<td>CLK2</td>
<td>9</td>
<td>O</td>
<td>Output clock 2</td>
</tr>
<tr>
<td>CLK3</td>
<td>8</td>
<td>O</td>
<td>Output clock 3</td>
</tr>
<tr>
<td>CLK4</td>
<td>19</td>
<td>O</td>
<td>Output clock 4</td>
</tr>
<tr>
<td>CLK5</td>
<td>17</td>
<td>O</td>
<td>Output clock 5</td>
</tr>
<tr>
<td>CLK6</td>
<td>16</td>
<td>O</td>
<td>Output clock 6</td>
</tr>
<tr>
<td>CLK7</td>
<td>15</td>
<td>O</td>
<td>Output clock 7</td>
</tr>
<tr>
<td>VC</td>
<td>3</td>
<td>I</td>
<td>VCXO control voltage input</td>
</tr>
<tr>
<td>SCL</td>
<td>4</td>
<td>I/O</td>
<td>I²C bus serial clock input. Pull-up to VDD core with 1 kΩ.</td>
</tr>
<tr>
<td>SDA</td>
<td>5</td>
<td>I/O</td>
<td>I²C bus serial data input. Pull-up to VDD core with 1 kΩ.</td>
</tr>
<tr>
<td>SSEN</td>
<td>6</td>
<td>I</td>
<td>Spread spectrum enable. High = enabled, Low = disabled.</td>
</tr>
<tr>
<td>OEB</td>
<td>7</td>
<td>I</td>
<td>Output driver enable. Low = enabled, High = disabled.</td>
</tr>
<tr>
<td>VDD</td>
<td>20</td>
<td>P</td>
<td>Core voltage supply pin</td>
</tr>
<tr>
<td>VDDOA</td>
<td>11</td>
<td>P</td>
<td>Output voltage supply pin for CLK0 and CLK1. See 6.2</td>
</tr>
<tr>
<td>VDDOB</td>
<td>10</td>
<td>P</td>
<td>Output voltage supply pin for CLK2 and CLK3. See 6.2</td>
</tr>
<tr>
<td>VDDOC</td>
<td>18</td>
<td>P</td>
<td>Output voltage supply pin for CLK4 and CLK5. See 6.2</td>
</tr>
<tr>
<td>VDDOD</td>
<td>14</td>
<td>P</td>
<td>Output voltage supply pin for CLK6 and CLK7. See 6.2</td>
</tr>
<tr>
<td>GND</td>
<td>Center Pad</td>
<td>P</td>
<td>Ground</td>
</tr>
</tbody>
</table>

1. I = Input, O = Output, P = Power
2. Input pins are not internally pulled up.
### 9.3. Si5351C 20-Pin QFN

#### Table 12. Si5351C Pin Descriptions

<table>
<thead>
<tr>
<th>Pin Name</th>
<th>Pin Number</th>
<th>Pin Type</th>
<th>Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>XA</td>
<td>1</td>
<td>I</td>
<td>Input pin for external crystal.</td>
</tr>
<tr>
<td>XB</td>
<td>2</td>
<td>I</td>
<td>Input pin for external crystal.</td>
</tr>
<tr>
<td>CLK0</td>
<td>13</td>
<td>O</td>
<td>Output clock 0.</td>
</tr>
<tr>
<td>CLK1</td>
<td>12</td>
<td>O</td>
<td>Output clock 1.</td>
</tr>
<tr>
<td>CLK2</td>
<td>9</td>
<td>O</td>
<td>Output clock 2.</td>
</tr>
<tr>
<td>CLK3</td>
<td>8</td>
<td>O</td>
<td>Output clock 3.</td>
</tr>
<tr>
<td>CLK4</td>
<td>19</td>
<td>O</td>
<td>Output clock 4.</td>
</tr>
<tr>
<td>CLK5</td>
<td>17</td>
<td>O</td>
<td>Output clock 5.</td>
</tr>
<tr>
<td>CLK6</td>
<td>16</td>
<td>O</td>
<td>Output clock 6.</td>
</tr>
<tr>
<td>CLK7</td>
<td>15</td>
<td>O</td>
<td>Output clock 7.</td>
</tr>
<tr>
<td>INTR</td>
<td>3</td>
<td>O</td>
<td>Interrupt pin. Open drain active low output, requires a pull-up resistor greater than 1 kΩ.</td>
</tr>
<tr>
<td>SCL</td>
<td>4</td>
<td>I</td>
<td>I²C bus serial clock input. Pull-up to VDD core with 1 kΩ.</td>
</tr>
<tr>
<td>SDA</td>
<td>5</td>
<td>I/O</td>
<td>I²C bus serial data input. Pull-up to VDD core with 1 kΩ.</td>
</tr>
<tr>
<td>CLKN</td>
<td>6</td>
<td>I</td>
<td>PLL clock input.</td>
</tr>
<tr>
<td>OEB</td>
<td>7</td>
<td>I</td>
<td>Output driver enable. Low = enabled, High = disabled.</td>
</tr>
<tr>
<td>VDD</td>
<td>20</td>
<td>P</td>
<td>Core voltage supply pin</td>
</tr>
<tr>
<td>VDDOA</td>
<td>11</td>
<td>P</td>
<td>Output voltage supply pin for CLK0 and CLK1. See 6.2</td>
</tr>
<tr>
<td>VDDOB</td>
<td>10</td>
<td>P</td>
<td>Output voltage supply pin for CLK2 and CLK3. See 6.2</td>
</tr>
<tr>
<td>VDDOC</td>
<td>18</td>
<td>P</td>
<td>Output voltage supply pin for CLK4 and CLK5. See 6.2</td>
</tr>
<tr>
<td>VDDOD</td>
<td>14</td>
<td>P</td>
<td>Output voltage supply pin for CLK6 and CLK7. See 6.2</td>
</tr>
<tr>
<td>GND</td>
<td>Center Pad</td>
<td>P</td>
<td>Ground.</td>
</tr>
</tbody>
</table>

**Notes:**
1. I = Input, O = Output, P = Power.
2. Input pins are not internally pulled up.
## 9.4. Si5351A 10-Pin MSOP

![Si5351A 10-MSOP Top View](image)

### Table 13. Si5351A 10-MSOP Pin Descriptions

<table>
<thead>
<tr>
<th>Pin Name</th>
<th>Pin Number</th>
<th>Pin Type*</th>
<th>Function</th>
</tr>
</thead>
<tbody>
<tr>
<td>XA</td>
<td>2</td>
<td>I</td>
<td>Input pin for external crystal.</td>
</tr>
<tr>
<td>XB</td>
<td>3</td>
<td>I</td>
<td>Input pin for external crystal.</td>
</tr>
<tr>
<td>CLK0</td>
<td>10</td>
<td>O</td>
<td>Output clock 0.</td>
</tr>
<tr>
<td>CLK1</td>
<td>9</td>
<td>O</td>
<td>Output clock 1.</td>
</tr>
<tr>
<td>CLK2</td>
<td>6</td>
<td>O</td>
<td>Output clock 2.</td>
</tr>
<tr>
<td>SCL</td>
<td>4</td>
<td>I</td>
<td>Serial clock input for the I²C bus. This pin must be pulled-up using a pull-up resistor of at least 1 kΩ.</td>
</tr>
<tr>
<td>SDA</td>
<td>5</td>
<td>I/O</td>
<td>Serial data input for the I²C bus. This pin must be pulled-up using a pull-up resistor of at least 1 kΩ.</td>
</tr>
<tr>
<td>VDD</td>
<td>1</td>
<td>P</td>
<td>Core voltage supply pin.</td>
</tr>
<tr>
<td>VDDO</td>
<td>7</td>
<td>P</td>
<td>Output voltage supply pin for CLK0, CLK1, and CLK2. See &quot;6.2. Power Supply Sequencing&quot; on page 22.</td>
</tr>
<tr>
<td>GND</td>
<td>8</td>
<td>P</td>
<td>Ground.</td>
</tr>
</tbody>
</table>

*Note:  I = Input, O = Output, P = Power
10. Ordering Information

An evaluation kit containing ClockBuilder Desktop software and hardware enable easy evaluation of the Si5351A/B/C. The orderable part numbers for the evaluation kits are provided in Figure 23.

*Note: The 10-MSOP is only available in the Si5351A variant.

Figure 22. Device Part Numbers

Figure 23. Si5351A/B/C Evaluation Kit
11. Package Outlines

11.1. 20-pin QFN
Table 14. 20-pin QFN Package Dimensions

<table>
<thead>
<tr>
<th>Dimension</th>
<th>Min</th>
<th>Nom</th>
<th>Max</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>0.80</td>
<td>0.85</td>
<td>0.90</td>
</tr>
<tr>
<td>A1</td>
<td>0.00</td>
<td>0.02</td>
<td>0.05</td>
</tr>
<tr>
<td>b</td>
<td>0.18</td>
<td>0.25</td>
<td>0.30</td>
</tr>
<tr>
<td>D</td>
<td></td>
<td></td>
<td>4.00 BSC</td>
</tr>
<tr>
<td>D2</td>
<td>2.65</td>
<td>2.70</td>
<td>2.75</td>
</tr>
<tr>
<td>e</td>
<td></td>
<td></td>
<td>0.50 BSC</td>
</tr>
<tr>
<td>E</td>
<td></td>
<td></td>
<td>4.00 BSC</td>
</tr>
<tr>
<td>E2</td>
<td>2.65</td>
<td>2.70</td>
<td>2.75</td>
</tr>
<tr>
<td>L</td>
<td>0.30</td>
<td>0.40</td>
<td>0.50</td>
</tr>
<tr>
<td>aaa</td>
<td></td>
<td></td>
<td>0.10</td>
</tr>
<tr>
<td>bbb</td>
<td></td>
<td></td>
<td>0.10</td>
</tr>
<tr>
<td>ccc</td>
<td></td>
<td></td>
<td>0.08</td>
</tr>
<tr>
<td>ddd</td>
<td></td>
<td></td>
<td>0.10</td>
</tr>
<tr>
<td>eee</td>
<td></td>
<td></td>
<td>0.10</td>
</tr>
</tbody>
</table>

**Notes:**
1. All dimensions shown are in millimeters (mm) unless otherwise noted.
3. This drawing conforms to the JEDEC Outline MO-220, variation VGGD-8.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.
11.2. 10-Pin MSOP

Table 15. 10-MSOP Package Dimensions

<table>
<thead>
<tr>
<th>Dimension</th>
<th>Min</th>
<th>Nom</th>
<th>Max</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>—</td>
<td>—</td>
<td>1.10</td>
</tr>
<tr>
<td>A1</td>
<td>0.00</td>
<td>—</td>
<td>0.15</td>
</tr>
<tr>
<td>A2</td>
<td>0.75</td>
<td>0.85</td>
<td>0.95</td>
</tr>
<tr>
<td>b</td>
<td>0.17</td>
<td>—</td>
<td>0.33</td>
</tr>
<tr>
<td>c</td>
<td>0.08</td>
<td>—</td>
<td>0.23</td>
</tr>
<tr>
<td>D</td>
<td>3.00</td>
<td>BSC</td>
<td></td>
</tr>
<tr>
<td>E</td>
<td>4.90</td>
<td>BSC</td>
<td></td>
</tr>
<tr>
<td>E1</td>
<td>3.00</td>
<td>BSC</td>
<td></td>
</tr>
<tr>
<td>e</td>
<td>0.50</td>
<td>BSC</td>
<td></td>
</tr>
<tr>
<td>L</td>
<td>0.40</td>
<td>0.60</td>
<td>0.80</td>
</tr>
<tr>
<td>L2</td>
<td>0.25</td>
<td>BSC</td>
<td></td>
</tr>
<tr>
<td>q</td>
<td>0</td>
<td>—</td>
<td>8</td>
</tr>
<tr>
<td>aaa</td>
<td>—</td>
<td>—</td>
<td>0.20</td>
</tr>
<tr>
<td>bbb</td>
<td>—</td>
<td>—</td>
<td>0.25</td>
</tr>
<tr>
<td>ccc</td>
<td>—</td>
<td>—</td>
<td>0.10</td>
</tr>
<tr>
<td>ddd</td>
<td>—</td>
<td>—</td>
<td>0.08</td>
</tr>
</tbody>
</table>

Notes:
1. All dimensions shown are in millimeters (mm) unless otherwise noted.
3. This drawing conforms to the JEDEC Solid State Outline MO-137, Variation C.
4. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.
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